

AMENDMENTS TO THE CLAIMS

Claims 1-14 (Cancelled).

15. (Previously Presented) A wiring board comprising:

an electrically insulating substrate; and

a wiring layer formed on a surface of said electrically insulating substrate by transferring said wiring layer from a wiring transfer sheet, an exposed portion of said surface of said electrically insulating substrate being a rough surface having a plurality of convexities, at least a portion of said convexities each having a diameter in a range of 0.5 μm to 5.0 μm at basis.

16. (Previously Presented) A wiring board comprising:

an electrically insulating substrate; and

a wiring layer formed on a surface of said electrically insulating substrate by transferring said wiring layer from a wiring transfer sheet, an exposed portion of said surface of said electrically insulating substrate being a rough surface having a plurality of convexities, at least a portion of said convexities each having a height in a range of 0.5 μm to 5.0 μm .

17. (Previously Presented) A wiring board comprising:

an electrically insulating substrate; and

a wiring layer formed on a surface of said electrically insulating substrate by transferring said wiring layer from a wiring transfer sheet, an exposed portion of said surface of said electrically insulating substrate being a rough surface having a plurality of convexities, at least a portion of said convexities each having a shape such that sections perpendicular to a height direction of each convexity are not uniform, and such that a maximum-sized section having a maximum area is located at an intermediate position between a basis and a top of each convexity.

18. (Previously Presented) The wiring board of claim 17, wherein at least a portion of said convexities each has a diameter in a range of 0.5 μm to 5.0 μm at the basis, and each has a diameter in a range of 1.0 μm to 10.0 μm at the maximum-sized section.

19. (Currently Amended) A wiring board comprising:

an electrically insulating substrate; and

a wiring layer formed on a surface of said electrically insulating substrate by transferring said wiring layer from a wiring transfer sheet, an exposed portion of said surface of said electrically insulating substrate being an exposed rough surface having a plurality of convexities, an exposed surface of said wiring layer being an exposed rough surface having a plurality of convexities formed of particles deposited by electrolytic plating, and a surface shape of said exposed rough surface of said electrically insulating substrate being substantially the same as a surface shape of said exposed rough surface of said wiring layer.

20. (Previously Presented) The wiring board of claim 19, wherein the wiring transfer sheet includes a carrier base, said wiring layer being formed on a transfer surface of the carrier base prior to being transferred to said electrically insulating substrate, at least a portion of the transfer surface of the carrier base being a roughened surface having concavities formed therein, and said convexities of said exposed rough surface of said electrically insulating substrate being complementary to the concavities of the roughened surface of the carrier base.

21. (Previously Presented) The wiring board of claim 20, wherein the carrier base comprises a first layer and a second layer made of a different material than the first layer, the transfer surface being formed on the first layer, the first layer being formed of a material not soluble with a material of said electrically insulating substrate.

22. (Previously Presented) The wiring board of claim 19, wherein said convexities of said exposed rough surface of said electrically insulating substrate occupy 50 % to 98 % of said exposed rough surface of said electrically insulating substrate.

23. (Previously Presented) The wiring board of claim 19, wherein said wiring board comprises a multilayer wiring board including at least two electrically insulating substrates.

24. (Previously Presented) The wiring board of claim 23, wherein said at least two electrically insulating substrates includes:

said electrically insulating substrate comprising a first electrically insulating substrate having said exposed rough surface; and

a second electrically insulating substrate having an exposed rough surface, said second electrically insulating substrate being superposed directly on said exposed rough surface of said first electrically insulating substrate and superposed directly on said exposed rough surface of said wiring layer formed on said surface of said first electrically insulating substrate.

25. (Previously Presented) The wiring board of claim 19, further comprising a component connected to said wiring layer and embedded in said electrically insulating substrate.

26. (Previously Presented) The wiring board of claim 25, wherein said electrically insulating substrate comprises a first electrically insulating substrate, said component being arranged to extend within said first electrically insulating substrate and an adjacent second electrically insulating substrate.

27. (Previously Presented) The wiring board of claim 26, wherein each of said first electrically insulating substrate and said second electrically insulating substrate has through-holes formed in a thickness direction thereof, said through-holes being filled with a conductive paste for

electrically connecting wiring layers arranged on surfaces of said first electrically insulating substrate and said second electrically insulating substrate.

28. (Previously Presented) The wiring board of claim 19, wherein said electrically insulating substrate has through-holes formed in a thickness direction thereof, said through-holes being filled with a conductive paste for electrically connecting wiring layers formed on opposite surfaces of said electrically insulating substrate.